

# SP5744PFK1AMLQ8R :Part Detail

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## General Information

|                                |                                                                                                  |
|--------------------------------|--------------------------------------------------------------------------------------------------|
| Part Number                    | SP5744PFK1AMLQ8R                                                                                 |
| Description                    | 32-bit MCU, Dual core Power Arch, 2.5MB Flash, 384K RAM, Flexray, 180MHz, -40/+125degC, LQFP 144 |
| Product Line                   | G9F5744P                                                                                         |
| PTI                            | JBSS                                                                                             |
| Material Type                  | Tested Packaged Device                                                                           |
| Life Cycle Description (code)  | PRODUCT RAPID GROWTH                                                                             |
| Status                         | Active                                                                                           |
| SafeAssure Functional Safety   | ISO 26262                                                                                        |
| Application/Qualification Tier | AUTO; >=10 YEARS APPLICATION LIFE                                                                |

## Package Information

|                                            |                                          |
|--------------------------------------------|------------------------------------------|
| Package Type and Termination Count         | LQFP 144                                 |
| Package Description and Mechanical Drawing | <a href="#">LQFP 144 20SQ1.4P0.5 C90</a> |
| Device Weight(g)                           | 1.31910                                  |
| Package Length (nominal)(mm)               | 20.000                                   |
| Package Width (nominal)(mm)                | 20.000                                   |
| Package Thickness (nominal)(mm)            | 1.500                                    |
| Maximum Height Above Board(mm)             | 1.600                                    |
| Tape & Reel                                | Yes                                      |

## Environmental and Compliance Information

|                                        |                                                                         |
|----------------------------------------|-------------------------------------------------------------------------|
| Pb-Free                                |                                                                         |
| RoHS Compliant                         |                                                                         |
| Halogen Free                           | Yes                                                                     |
| Material Composition Declaration (MCD) | <a href="#">Download MCD Report</a> <a href="#">Download MCD Report</a> |
| RoHS Certificate of Analysis (CoA)     | <a href="#">Contact Us</a>                                              |
| 2nd Level Interconnect                 | e3                                                                      |

|                                         |                                                                            |
|-----------------------------------------|----------------------------------------------------------------------------|
| Moisture Sensitivity Level (MSL)        | 3                                                                          |
| Floor Life                              | 168 HOURS                                                                  |
| Peak Package Body Temperature (PPT)(°C) | 260                                                                        |
| Maximum Time at Peak Temperature (s)    | 40                                                                         |
| Number of Reflow Cycles                 | 3                                                                          |
| REACH SVHC                              | <a href="#">NXP REACH Statement</a>                                        |
| UL94 (plastics flammability test)       | V0;Burning stops within 10 seconds on a vertical specimen;no drips allowed |

## Manufacturing Information

|                 |     |
|-----------------|-----|
| Micron Size(μm) | .05 |
|-----------------|-----|

## Ordering Information

|                                                           |             |
|-----------------------------------------------------------|-------------|
| Minimum Package Quantity (MPQ)                            | 500         |
| MPQ Container                                             | REEL        |
| Exempt from Minimum Delivery Value                        | Yes         |
| Preferred Order Quantity (POQ)                            | 500         |
| POQ Container                                             | BOX         |
| Export Control Classification Number (US)                 | 3A991A2     |
| Harmonized Tariff (                                       |             |
| CCATS Document                                            | -           |
| ENC Status                                                | -           |
| Other Trade Compliance Documents                          | -           |
| <a href="#">Budgetary Price excluding tax(US Currency</a> | 1 @ US each |
| Order                                                     |             |

## Operating Characteristics

|                               |   |
|-------------------------------|---|
| Sample Exception Availability | N |
|-------------------------------|---|

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